



Material Content Data Sheet



Sales Product Name		IPB108N15N3 G		Issued		29. August 2013			
MA#		MA000771440							
Package		PG-TO263-3-2		Weight*		1468.16 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	10.752	0.73	0.73	7324	7324	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174		
	non noble metal	copper	7440-50-8	851.691	58.00	58.08	580109	580864	
wire	non noble metal	aluminium	7429-90-5	10.940	0.75	0.75	7451	7451	
encapsulation	organic material	carbon black	1333-86-4	8.648	0.59		5890		
	plastics	epoxy resin	-	95.125	6.48		64792		
	inorganic material	silicondioxide	60676-86-0	472.741	32.20	39.27	321997	392679	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6577	6577	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.182	0.01		124		
	non noble metal	tin	7440-31-5	0.145	0.01		99		
	non noble metal	lead	7439-92-1	6.939	0.47	0.49	4726	4949	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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